

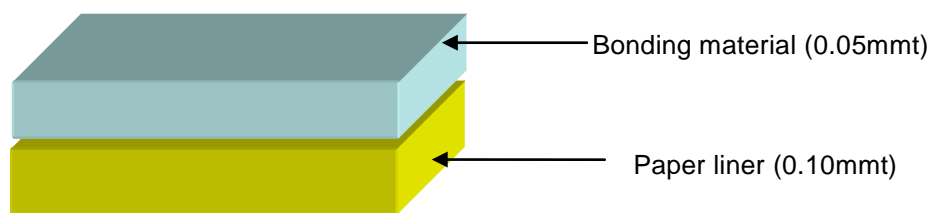
Heat moist resistant thermal bonding sheet

FB-ML4-50S(K)

1.Feature

FB-ML4-50S(K) is a substrate free thermal bonding sheet, which shows excellent bonding strength and bonding maintenance at heat moist circumstance. Excellent bonding power is available for various adherence bodies by instant heat press.

2.Configuration



Picture-1

3.General properties

Table-1

Item	Unit	Result	Measuring method
Thickness	mm	0.051	1/1000 mm dial gauge
Specific gravity	-	1.31	ASTM-D1622
180 degrees peeling Strength	N/10mm	30.2	Adhesive condition: 140°C×2MPa×2sec(laminate)+ (PI side) 170°C×1MPa×4sec Adherend:PI film/PET-G Tensile speed:50mm/min
Softening point	°C	90°C	TMA
Shore hardness	-	82	ASTM-D785
Tensile strength	N/mm ²	7.8 (MD)	ASTM-D1000
		8.3 (TD)	
Elongation	%	745.3 (MD)	ASTM-D1000
		824.3 (TD)	

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